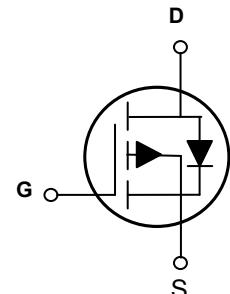
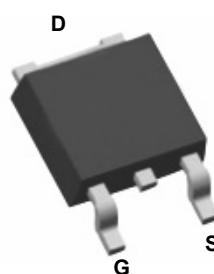


## Main Product Characteristics

$V_{DSS}$	-60V
$R_{DS(ON)}$	13mΩ (typ.)
$I_D$	-70A



TO-252 (DPAK)

Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- High power and current handing capability
- Fully avalanche rated



## Description

The SSFD6017 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^\circ C$ ), $V_{GS}=10V^1$	$I_D$	-70	A
Drain Current-Continuous ( $T_C=100^\circ C$ ), $V_{GS}=10V^1$		-55	A
Drain Current-Pulsed <sup>2</sup>	$I_{DM}$	-280	A
Pulsed Source Current (Body Diode) <sup>2</sup>	$I_{SM}$	-280	A
Maximum Power Dissipation ( $T_C=25^\circ C$ ) <sup>3</sup>	$P_D$	170	W
Single Pulse Avalanche Energy ( $L=0.3mH$ )	$E_{AS}$	300	mJ
Single Pulse Avalanche Current ( $L=0.3mH$ )	$I_{AS}$	44	A
Junction-to-Ambient ( $t \leq 10s$ ) <sup>4</sup>	$R_{\theta JA}$	62	°C/W
Maximum Junction-to-Case <sup>5</sup>	$R_{\theta JC}$	0.73	°C/W
Operating Junction Temperature Range	$T_J$	-55 To +150	°C
Storage Temperature Range	$T_{STG}$	-55 To +150	°C

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-60	-	-	V
Drain-to-Source Leakage Current	$I_{\text{DS}}^{\text{SS}}$	$V_{\text{DS}}=-60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Drain-to-Source Leakage Current		$V_{\text{DS}}=-60\text{V}, V_{\text{GS}}=0\text{V}$ $T_J=125^\circ\text{C}$	-	-	-50	$\mu\text{A}$
Gate-to-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-	-3	V
Drain Static-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-23\text{A}$	-	12	17	$\text{m}\Omega$
		$V_{\text{GS}}=-10\text{V},$ $I_{\text{D}}=-23\text{A} T_J=125^\circ\text{C}$	-	22	-	$\text{m}\Omega$
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{\text{DD}}=-40\text{V}, I_{\text{D}}=-30\text{A}$ $V_{\text{GS}}=-10\text{V}$	-	110	150	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	16.5	30	
Gate-Drain Charge	$Q_{\text{gd}}$		-	23.2	40	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-30\text{V}, R_G=3\Omega$ $R_L=1.5\Omega, V_{\text{GS}}=-10\text{V},$ $I_{\text{D}}=-20\text{A}$	-	8.0	-	nS
Rise Time	$t_r$		-	26.5	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	105.2	-	
Fall Time	$t_f$		-	142.1	-	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-25\text{V}, V_{\text{GS}}=0\text{V},$ $F=1\text{MHz}$	-	4802	-	pF
Output Capacitance	$C_{\text{oss}}$		-	288	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	273	-	
Gate Resistance	$R_g$	$F=1\text{MHz}$	-	5.56	-	$\Omega$
<b>Source-Drain Ratings and Characteristics</b>						
Maximum Body-Diode Continuous Current	$I_s$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-70	-	A
Maximum Body-Diode Pulse Current	$I_{\text{SM}}$	$V_{\text{GS}}=0\text{V}, I_s=-10\text{A},$ $T_J=25^\circ\text{C}$	-	-280	-	A
Diode Forward Voltage	$V_{\text{SD}}$		-	-0.74	-1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F=-20\text{A}$ $di/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	-	22.3	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	21.5	-	nC

**Notes:**

- Calculated continuous current based on maximum allowable junction temperature.
- Repetitive rating; pulse width limited by max. junction temperature.
- The power dissipation  $P_D$  is based on max. junction temperature, using junction-to-case thermal resistance.
- The value of  $R_{\text{thJA}}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$

## Test Circuits and Waveforms

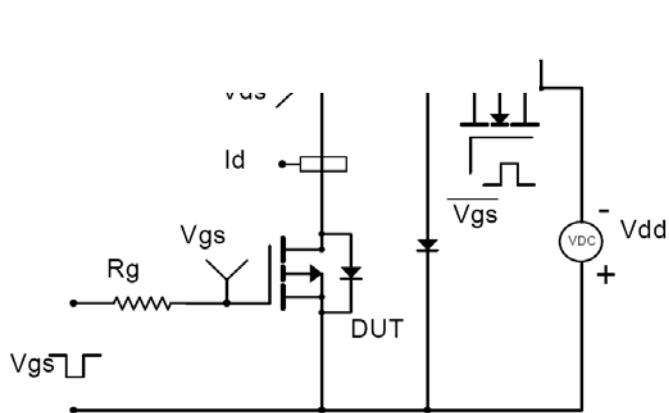


Figure 1. EAS Test Circuit

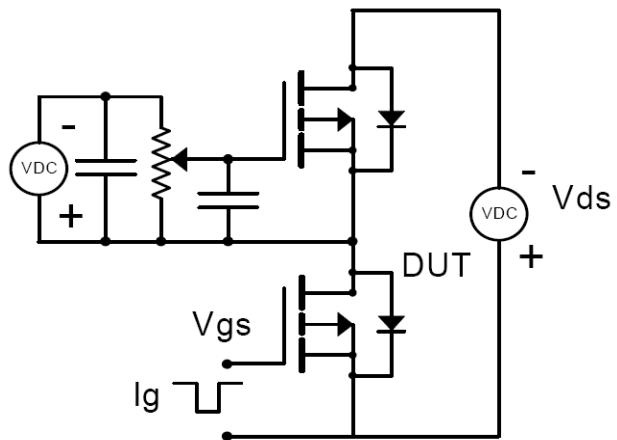


Figure 2. Gate Charge Test Circuit

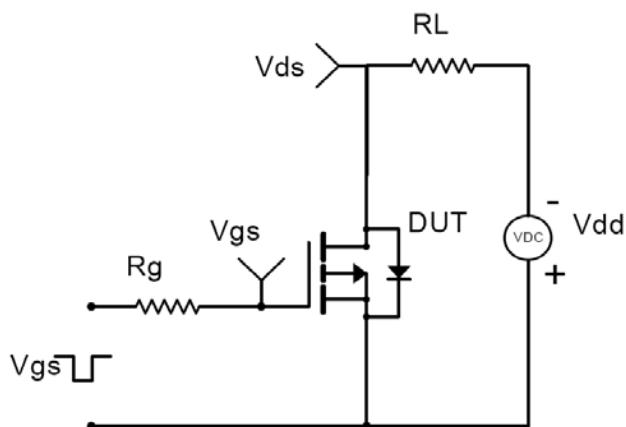


Figure 3. Switching Time Test Circuit

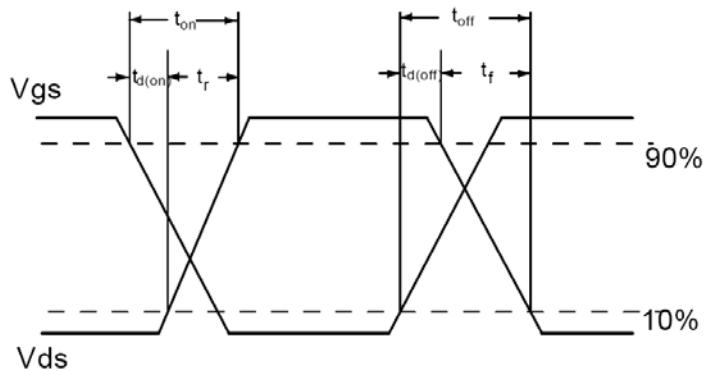
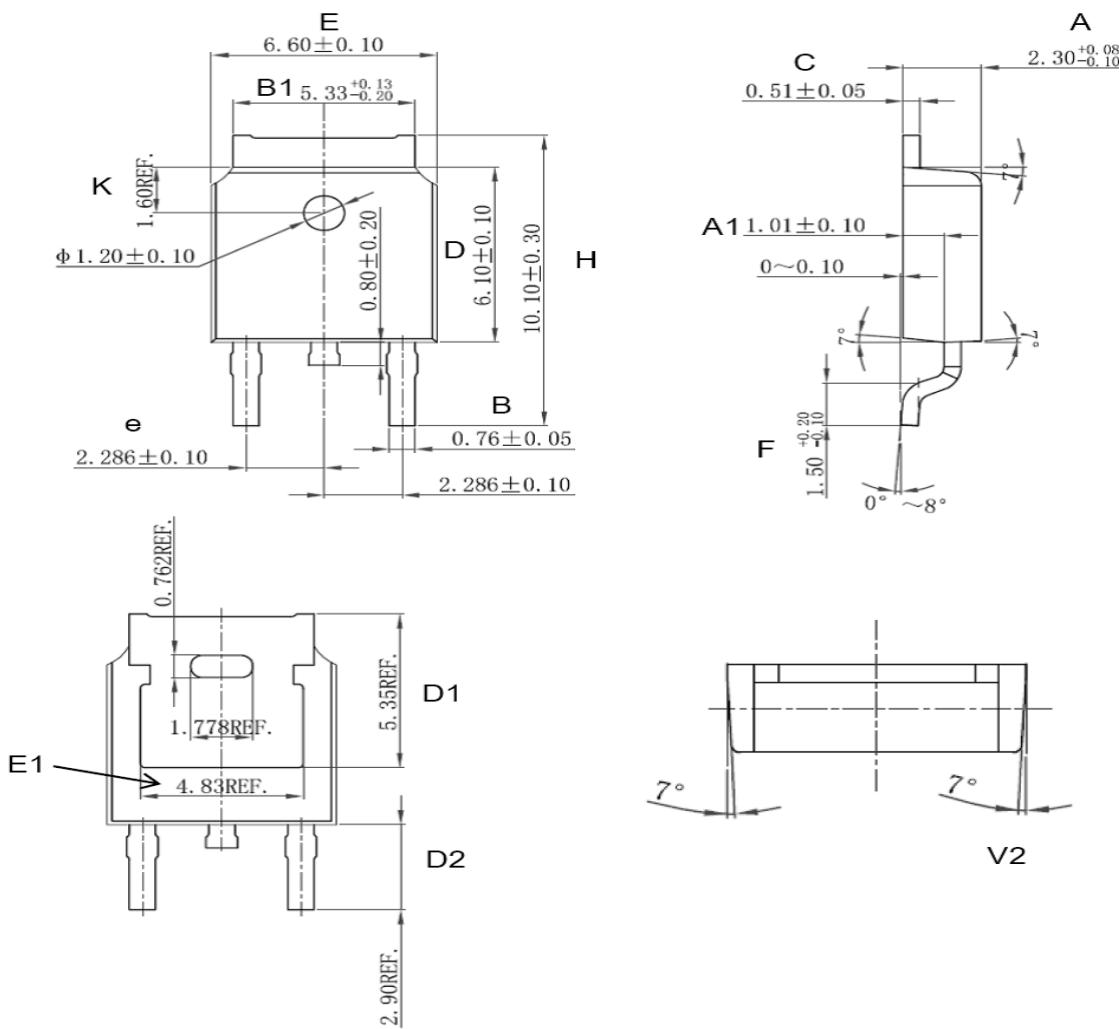


Figure 4. Switching Waveforms

### Package Outline Dimensions (TO-252/DPAK)



Symbol	Dimension In Millimeters			Dimension In Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.200	2.300	2.380	0.087	0.091	0.094
A1	0.910	1.010	1.110	0.036	0.040	0.044
B	0.710	0.760	0.810	0.028	0.030	0.032
B1	5.130	5.330	5.460	0.202	0.210	0.215
C	0.460	0.510	0.560	0.018	0.020	0.022
D	6.000	6.100	6.200	0.236	0.240	0.244
D1	5.350 (REF)			0.211 (REF)		
D2	2.900 (REF)			0.114 (REF)		
E	6.500	6.600	6.700	0.256	0.260	0.264
E1	4.83 (REF)			0.190 (REF)		
e	2.186	2.286	2.386	0.086	0.090	0.094
H	9.800	10.100	10.400	0.386	0.398	0.409
F	1.400	1.500	1.700	0.055	0.059	0.067
K	1.600 (REF)			0.063 (REF)		
V2	$8^\circ$ (REF)			$8^\circ$ (REF)		